

<b>Notice of References Cited</b>	Application/Control No. 10/020,638	Applicant(s)/Patent Under Reexamination MA ET AL.	
	Examiner James Mitchell	Art Unit 2827	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,388,321	05-2002	Hirai et al.	174/259
	B	US-5,494,981	02-1996	Gorodisher et al.	525/504
	C	US-6,331,446	12-2001	Cook et al.	438/106
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N	200225211	07-2001	Japan	Chun	---
	O	62-275123	11-1987	Japan	Toray	---
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	L. Nguyen, "Solder Joint Shape Formation Under Constrained Boundaries in Wafer Level Underfill", 2000 IEEE
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.